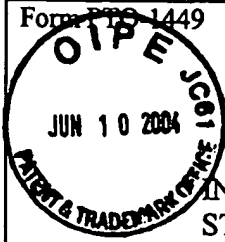


Form PTO-1449		U.S. Department of Commerce Patent and Trademark Office		Atty. Docket No. H0005211 (HON0002/US)		Serial No. 10/712,591	
		INFORMATION DISCLOSURE STATEMENT BY APPLICANT					
		Applicant Zou et al.		Filing Date November 13, 2003		Group	
U.S. PATENT DOCUMENTS							
Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
MK		4,731,757	03/1988	Daughton et al.			
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OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)							
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		H. Aoki et al., "A Degradation-Free Cu/HSQ Damascene Technology using Metal Mask Patterning and Post-CMP Cleaning by Electrolytic Ionized Water," <i>IEDM 97</i> , pp. 777-780, 1997					
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[Signature] 07/29/05